MA2Z784 (MA784)

Silicon epitaxial planar type

For super high speed switching For small current rectification

■ Features

- High-density mounting is possible
- Forward current (Average) $I_{F(AV)} = 100 \text{ mA}$ rectification is possible
- Optimum for high frequency rectification because of its short reverse recovery time t_{rr}
- Low forward voltage V_F and good rectification efficiency

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	30	V
Repetitive peak reverse voltage	V _{RRM}	30	V
Peak forward current	I_{FM}	300	mA
Forward current (Average)	I _{F(AV)}	100	mA
Non-repetitive peak forward surge current *	I_{FSM}	1	A
Junction temperature	T_{j}	125	°C
Storage temperature	T_{stg}	-55 to +125	°C

Note) *: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)

Unit: mm 1.25±0.1 0.35±0.1 0 to 0.1 1.25±0.1 0 to 0.1 0.7±0.1 0.7±0.1 0.7±0.1 0.7±0.1 0.7±0.1 0.7±0.1 0.7±0.1 0.16±0.1 0.1

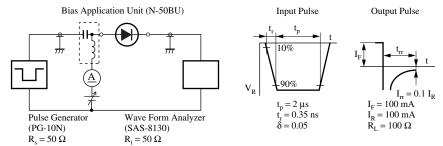
Marking Symbol: 2D

\blacksquare Electrical Characteristics $T_a = 25 ^{\circ} C \pm 3 ^{\circ} C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V _F	$I_F = 100 \text{ mA}$			0.55	V
Reverse current	I_R	$V_R = 30 \text{ V}$			15	μΑ
Terminal capacitance	C _t	$V_R = 0 V, f = 1 MHz$		20		pF
Reverse recovery time *	t _{rr}	$I_F = I_R = 100 \text{ mA}$		2.0		ns
		$I_{rr} = 0.1 I_{R}, R_{L} = 100 \Omega$				

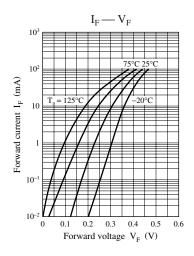
- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
 - This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
 - 3. Absolute frequency of input and output is 250 MHz.

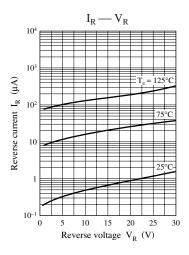
4.*: t_{rr} measurement circuit

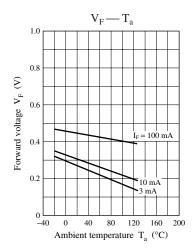


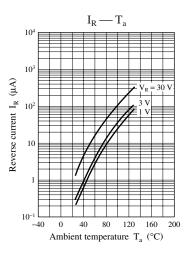
Note) The part number in the parenthesis shows conventional part number.

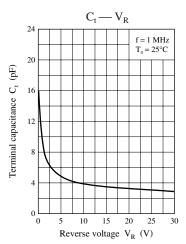
Panasonic











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